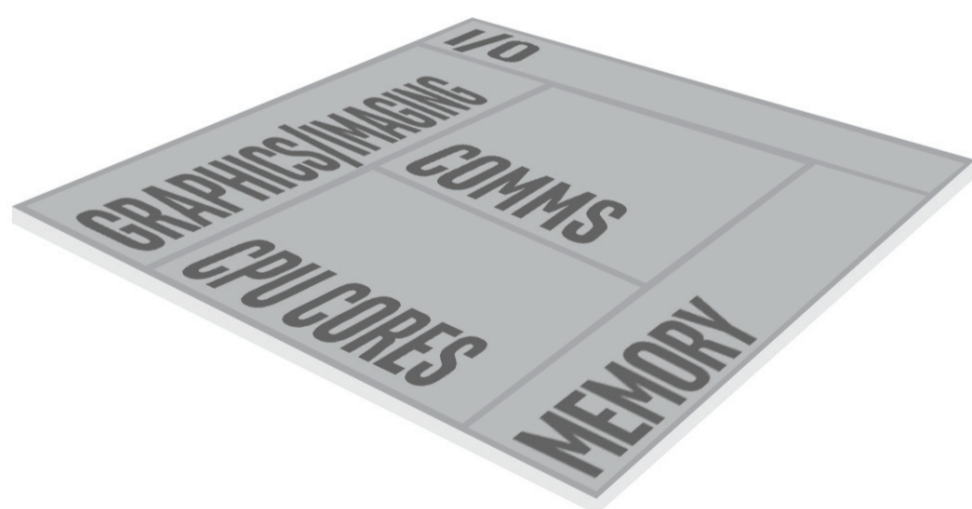


MIX AND MATCH INNOVATION

A new heterogeneous model is evolving to drive product innovation for demanding and highly specialized data-intensive workloads – such as artificial intelligence and autonomous driving. A heterogeneous “mix and match” approach combines diverse powerful technology IP and new packaging innovations that give product designers and architects much more flexibility and faster cycle times.

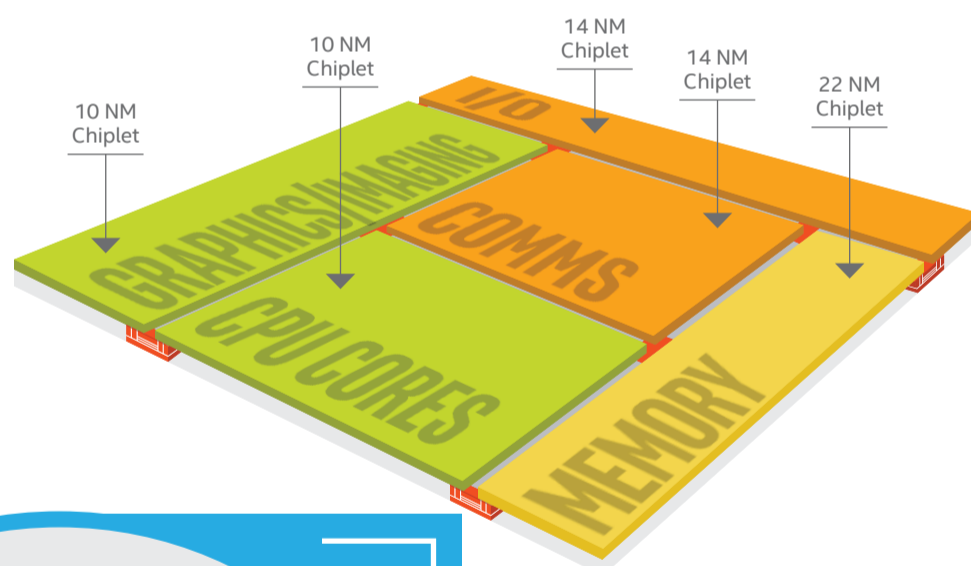
MONOLITHIC CHIP

A singular piece of silicon, constructed as a unit



CHIPLETS

A heterogeneous collection of “chiplets” integrated as one device



AN INTEL INNOVATION

Embedded Multi-die Interconnect Bridge (EMIB) is a no-compromise die-to-die packaging interconnect with high performance, low cost, and high density.

[Read more about EMIB >](#)

CHIPLET LIBRARY

